

LINEAR TECHNOLOGY MATERIALS DECLARATION

(Engineering Calculation)

MSCP

(printed on: 2014-01-20 00:54:03)

TOTAL MASS (g): 0.027645

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002216	1000000	80159.09375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.010433	975000	377391.5625		
		Iron (Fe)	7439-89-6	0.000257	24000	9256.42871094		
		Phosphorus (P)	7723-14-0	0.000003	300	108.518623352		
		Zinc (Zn)	7440-66-6	0.000007	700	253.210113525		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		<b>Lead Frame Total:</b>				<b>0.010700</b>	<b>1000000</b>	<b>38700.75</b>
		Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0
Exter. Plating Sn	7440-31-5			0.000710	1000000	25683.6425781		
<b>External Plating Total:</b>						<b>0.000710</b>	<b>1000000</b>	<b>25683.6425781</b>
Inter. Plating Ni	7440-02-0			0.000000	0	0		
Inter. Plating Ag	7440-22-4			0.000086	1000000	3110.86694336		
<b>Internal Plating Total:</b>						<b>0.000086</b>	<b>1000000</b>	<b>3110.86694336</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000738	750000	26695.5800781		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000246	250000	898.52734375		
		<b>Die Attach Total:</b>				<b>0.000984</b>	<b>1000000</b>	<b>38594.109375</b>
		Encapsulation	MULTIAROMATIC RESIN BOND FREE	Resin (EP)	0.001314	103000	47511.1523438	
				Bromine (Br)	40093-93-8	0.000000	0	0
Silica (SiO2)	60676-86-0			0.011420	895000	413094.21875		
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0		
Metal Hydroxide				0.000000	0	0		
Carbon Black (C)	1333-86-4			0.000026	2000	940.494889941		
<b>Encapsulation Total:</b>						<b>0.012760</b>	<b>1000000</b>	<b>461565.875</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000189	1000000	6836.6728156		

TOTAL MASS (g): 0.027645